

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

28.04.2026

**WÜRTH
ELEKTRONIK**
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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C-RS Panasonic R-F770-ED 18-50-00

50200950

18
50

VS



A-RAS-FR4-PP-106-H72-TG170-LowFlow-EM...

50203100

50

2 A01

C-RS-FR4-ML-0.610mm-018+018-TG150-HF-...

50203032

18
610
18

L2

3 A02

L3

B00

C-RAS-FR4-PP-106-H71-TG150-HF-EM-37B(...

50202996

91

4

C-RAS-FR4-PP-106-H71-TG150-HF-EM-37B(...

50202996

0

5

A-RS Kupferfolie-018my 330x490mm

50200238

18

RS

6

Thickness after Pressing

B00:

890 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

990 µm

Dmin:

790 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1000 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

1100 µm

Dmin:

900 µm

Measuring point:

(05) over SM and galv. Cu; both sides

nominal:

873 µm

Version 1.2.20.35

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